

#2/575  
02/21/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: To Be Assigned  
Examiner: To Be Assigned

jc979 U.S. PRO  
10/022268  
12/20/01

In re PATENT APPLICATION of

Applicant(s) : TERUI et al. )  
Appln. No. : To Be Assigned )  
Filed : December 20, 2001 )  
For : SEMICONDUCTOR PACKAGE AND )  
METHOD OF FABRICATING SAME )  
Atty. Dkt. : OKI 286 )

**INFORMATION  
DISCLOSURE  
STATEMENT**

Commissioner for Patents  
Washington, D.C. 20231

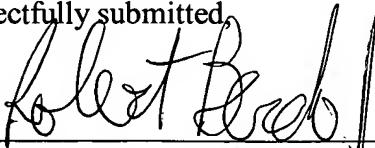
Sir:

This is an information disclosure statement submitted in compliance with the timing requirements of 37 C.F.R. §1.97(b)(1).

Attached are copies of a U.S. patent and a Japanese patent. The relevance of the Japanese patent can be gleaned from the attached English-language Abstract. The patents are listed on the attached Form PTO-1449.

Since this Information Disclosure Statement is being filed with the application, no certification or fee is required, and the requirements of 37 C.F.R. §§1.97 and 1.98 are deemed to be fully met as to the document submitted. Consideration of the submitted document is respectfully requested.

Respectfully submitted,



Robert H. Berdo, Jr. (Reg. No. 38075)  
RABIN & BERDO, P.C.  
CUSTOMER NO. 23995  
(202) 659-1915  
(202) 659-1898 fax

December 20, 2001

Date

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